

Welcome to O-Leading

O-Leading is committed to being the partner of the one stop solution in the EMS supply chain, including PCB design, PCB manufacturing and PCB assembly (PCBA). We supply some of the most advanced PCB technologies, including HDI PCBs, multilayer PCBs, rigid-flexible PCBs. We are able to support from the rapid rotation prototype to medium and mass production. [OEM Pcb prototype manufacturer china](#)

In general, our global customers are very impressed with our services: quick response, competitive price and quality commitment. Providing more valuable technical service and a global solution is the way O-leaders move forward.

Looking to the future, O-Leading will focus on innovation and the development of electronic production technology as always and will make constant efforts on the one-stop PCB and PCBA service to provide first-class services and create more value for our customers.

Product description

Quick Info

Place of origin	Guangdong, China (mainland)	Brand name	O-leader
Basic material	FR-4, Aluminum	Copper thickness	0.5 ounces-5 ounces
Min. Hole size	0.2mm	Min. Line width	0.2mm
Surface finish	diving gold, OSP, lead-free HASL	Min. Line Spacing	0.2mm
applicable to	led, mobile phone, air conditioners, washing machines	character	Industrial control PCB
certified	ISO9001, UL, RoHS, SGS	Q / CTN	10PCS-100PCS
weight	0.01 kg -5 kg	MOQ	10 pieces
Model number	pcba manufacturer pcb assembly power bank	Thickness of the card	0.1-5mm
color	blue, red, green, black. yellow	price	\$ 0.1- \$ 10
type design	customer's requirement	cut it	0.01m3-10m3

Country of origin: [China Rigid-flexible PCB manufacturer](#)

Production capacity

16 years of professional production of OEM PCB boards

article	2014		2015 ~ 2016		2017 ~ 2018	
	Volume	Sample	Volume	Sample	Volume	Sample
Counting levels	32	42	38	44	42	48
Line / min space (μm)	50/50	40/45	40/45	40/40	35/40	35/35
Hole min diameter (mm)	00:15	00:10	00:15	00:10	00:15	00:10
Proportions by PTH	14: 1	16: 1	16: 1	18: 1	18: 1	20: 1

N + C + N	4 + C + 4	5 + C + 5	5 + C + 5	6 + C + 6	5 + C + 5	6 + C + 6
Any layer interconnection	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6
Plate filling by	YUP	-	YUP	-	YUP	-
Min. Core thickness (excluding copper) (μm)	50	40	40	30	40	30
Min. Diameter of the laser drill (μm)	75	65	65	50	50	40
Street buried hole / stacked away	YUP	-	YUP	-	YUP	-
Material	FR4, Megtron, Nelco, Rogers, Heavy Copper, etc.					
Built-in capacitor PCB	YUP	-	YUP	-	YUP	-
Surface process	Lead free HASL, ENIG, OSP, immersion silver, immersion tin, Flash gold, gold plating, selective hard gold plating, Weldable mask, carbon ink					

O-LEADING
To Be Reliable, To Be Valuable



www.o-leading.com

Our team



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT



certifications





No. SZXEC1900530401

Date: 30 Mar 2019

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O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313, FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ

Date of Sample Received : 22 Mar 2019

Testing Period : 22 Mar 2019 - 30 Mar 2019

Test Requested : Selected test(s) as requested by client.

Test Method : Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PDBEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina Fan
Approved Signatory



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No. SZXEC1900530401

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Test Results :

Test Part Description:

Specimen No.	SGS Sample ID	Description
SN1	SZX19-005304.001	Green™PCB

Remarks :

(1) $1 \text{ mg/kg} = 1 \text{ ppm} = 0.0001\%$

(2) MDL = Method Detection Limit

(3) ND = Not Detected (< MDL)

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Q27
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tri bromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tri bromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



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Printed and e-Certificate. Please contact us at info@spa.com or at <tel:+34915183071>

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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max		Max		Meets C		UL796 T
	Min	Min			Area	Solder	Oper	Flame			
	mm(in)	mm(in)			Diam	Limits	Temp	Class			
						C	sec	C			
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Packaging and delivery

Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Process capability

PCB production features

Layer count: 1 layer-32 layers

Finished copper thickness □ 1 / 3oz-12oz

Min line width / internal spacing □ 3.0mil / 3.0mil

Min line width / external spacing: 4.0mil / 4.0mil

Maximum aspect ratio: 10: 1

Board thickness □ 0.2mm-5.0mm

Maximum panel size (inches): 635 * 1500mm

Minimum hole size: 4mil

Plated hole tolerance: +/- 3mil

Blind / Buried Vias (All types): YES

Via Fill (conductive, non-conductive): YES

Base material: FR-4, FR-4hg Tg. Halogen-free material, Rogers, Aluminum base,polyimide,

Heavy copper

Surface finishes: HASL, OSP, ENIG, HAL-LF, silver mmmm,Immersion Tin, golden fingers, carbon ink

SMT production capacity

PCB material: FR-4, CEM-1, CEM-3, aluminum based board

Maximum PCB size: 510x460mm

Min PCB size: x 50x50mm

PCB thickness □ 0.5mm-4.5mm

Board thickness □ 0.5-4mm

Min component dimensions: 0201

Standard chip size component: 0603 and above

Maximum component height □ 15mm

Minimum lead pitch: 0.3 mm

Ball pitch BGA min: 0.4mm

Positioning accuracy: +/- 0.03 mm